AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [1052] with the following amended paragraph:

[1052] Referring to FIG 5B, another exemplary integrated circuit die cross-section 550 illustrates a Faraday cage surrounding an inductor structure (i.e., inductor 525). Top plate ~~552~~ 553 is formed in a redistribution layer by, e.g., under bump metallurgy. Sidewalls 556 and 550 are formed in redistribution layers. Rows of vias in the typical integrated circuit layers, e.g., rows 564 and 562, are electrically coupled to sidewalls 556 and 550.

Please replace paragraph [1068] with the following amended paragraph:

[1068] Exemplary electrically conductive links 904, 906, 908, and 910 are 5μm wide and are formed in a first traditional metal layer and a second traditional metal layer (e.g., metal-1 and metal-2), the same metal layers as bottom plate 901. Like bottom plate 901, electrically conductive links 904, 906, 908, and 910 may be formed in any other traditional metal layer, an ultra-thick metal layer, two or more sub-links, a redistribution metal layer, other suitable materials, or any combination thereof. The four electrically conductive links extend from respective segments of the aperture perimeter to opposite segments of the aperture perimeter. These links intersect at 45, 90, and 135 degree angles at their respective midpoints. However, any suitable number of links may be used, intersecting at any suitable angle. In some embodiments of the present invention, a center linking structure 966 may be included to provide a 90 degree intersection interface for sub-links of links ~~902,~~ 904, 906, ~~and~~ 908, and 910 to prevent 45 degree intersections of links ~~902,~~ 904, 906, ~~and~~ 908, and 910.

Please replace paragraph [1070] with the following amended paragraph:

[1070] Referring to FIG. 9C, links ~~902,~~ 904, 906, ~~and~~ 908, and 910 form eight "wedges" in the aperture. These wedges reduce the effective aperture by allowing currents to flow that oppose external electromagnetic signals entering the aperture. These currents are orthogonal to current flow in the inductor, thus, the paths formed in the aperture do not allow a current to flow that opposes the electromagnetic field of the inductor. In one embodiment, the configuration of FIG. 9C reduces by 6dB, the amount of coupling in the inductor from external sources, as compared to the configuration of FIG. 9A.

Please replace paragraph [1071] with the following amended paragraph:

[1071] Referring to FIG. 10, an exemplary configuration that further reduces an effective aperture includes links 1004, 1006, 1008, and 1010 and at least one additional electrically conductive link (e.g., electrically conductive links 1012 and 1014, illustrated without inductor 912 for ease of viewing) across aperture 1002. Exemplary electrically conductive links 1012 and 1014 are 5μm wide and are formed in a first traditional metal layer and a second traditional metal layer (e.g., metal-1 and metal-2), the same metal layers as bottom plate 901. Like bottom plate 901, electrically conductive links may be formed in any other traditional metal layer, an ultra-thick metal layer, a redistribution metal layer, other suitable materials, or any combination thereof. Electrically conductive links 1012 and 1014 form additional paths for induced currents to form that counteract external electromagnetic signals. Note that these additional links do not form a path that easily allows an induced current to form that counteracts the electromagnetic flux of inductor 912. In an exemplary process, electrically conductive links (e.g., 1012 and 1014) intersect corresponding ones of electrically conductive links ~~904, 906, 908, and 910~~ 1004, 1006, 1008, and

1010 at 90 degree angles. However, any suitable number of links may be used, intersecting at any suitable angle to reduce the aperture size.